

### **ABSTRACT OF THE DISCLOSURE**

[0031] A modular power semiconductor module for mounting on a heat sink comprises a plurality of partial modules, each having a base plate and a framelike housing as well as terminal elements for load terminals and auxiliary terminals. Adjacent partial modules are assembled into a complete power semiconductor module by means of a cap that fixes the partial modules relative to one another and/or by means of connections that fix the various partial modules relative to one another.